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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Guenther et al.  
Serial No. : 10/065,254  
Filed : September 30, 2002

Art Unit : 2815  
Examiner : Jasmine Clark  
Conf. No. : 5658

Title : ENCAPSULATION OF ELECTROLUMINESCENT DEVICES WITH SHAPED SPACERS

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

TRANSMITTAL OF PRIORITY DOCUMENT UNDER 35 USC §120

Applicant hereby confirms a claim of priority under 35 USC §120 to the following application:

International Application No. PCT/SG1999/000143 filed December 17, 1999.

A certified copy of the application from which priority is claimed is submitted herewith.

Please apply any charges or credits to Deposit Account No. 06-1050.

Respectfully submitted,

Date: 5/7/08

  
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This is to certify that the annexed is a true copy of the following international application as filed with the Registry as the receiving Office and of any corrections thereto.

Date of Filing : 17 DEC 1999

Application Number : PCT/SG1999/000143

Applicant(s) / Proprietor(s) of Patent : OSRAM OPTO SEMICONDUCTORS GMBH & CO. OHG;  
INFINEON TECHNOLOGIES ASIA PACIFIC PTE LTD

Title of Invention : ENCAPSULATION FOR ORGANIC LED DEVICE



Chung Ka Yee (Ms)  
Assistant Registrar  
*for* REGISTRAR OF PATENTS  
SINGAPORE

23 Apr 2008

PCT

## REQUEST

The undersigned requests that the present international application be processed according to the Patent Cooperation Treaty.

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PCT/SG 99/00143

International Application No.

17 DECEMBER 1999 (17-12-1999)

International Filing Date

REGISTRY OF PATENTS (SINGAPORE)  
PCT INTERNATIONAL APPLICATION

Name of receiving Office and "PCT International Application"

Applicant's or agent's file reference  
(if desired) (12 characters maximum) 2809.50004 PCTBox No. I TITLE OF INVENTION  
ENCAPSULATION FOR ORGANIC LED DEVICE

## Box No. II APPLICANT

Name and address: (Family name followed by given name; for a legal entity, full official designation. The address must include postal code and name of country. The country of the address indicated in this Box is the applicant's State (that is, country) of residence if no State of residence is indicated below.)

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## Box No. III FURTHER APPLICANT(S) AND/OR (FURTHER) INVENTOR(S)

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 Further applicants and/or (further) inventors are indicated on a continuation sheet.

## Box No. IV AGENT OR COMMON REPRESENTATIVE; OR ADDRESS FOR CORRESPONDENCE

The person identified below is hereby/has been appointed to act on behalf of the applicant(s) before the competent International Authorities as:

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## Continuation of Box No. III FURTHER APPLICANT(S) AND/OR (FURTHER) INVENTOR(S)

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This person is:

- applicant only  
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This person is:

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Further applicants and/or (further) inventors are indicated on another continuation sheet.

## Box No.V DESIGNATION OF STATES

The following designations are hereby made under Rule 4.9(a) (mark the applicable check-boxes; at least one must be marked):

## Regional Patent

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## Box No. VI PRIORITY CLAIM

 Further priority claims are indicated in the Supplemental Box.

Filing date of earlier application (day/month/year)	Number of earlier application	Where earlier application is:		
		national application: country	regional application: regional Office	international application: receiving Office
item (1)				
item (2)				
item (3)				

The receiving Office is requested to prepare and transmit to the International Bureau a certified copy of the earlier application(s) (only if the earlier application was filed with the Office which for the purposes of the present international application is the receiving Office) identified above as item(s): \_\_\_\_\_

\* Where the earlier application is an ARIPO application, it is mandatory to indicate in the Supplemental Box at least one country party to the Paris Convention for the Protection of Industrial Property for which that earlier application was filed (Rule 4.10(b)(ii)). See Supplemental Box.

## Box No. VII INTERNATIONAL SEARCHING AUTHORITY

Choice of International Searching Authority (ISA)  
(if two or more International Searching Authorities are competent to carry out the international search, indicate the Authority chosen; the two-letter code may be used):

ISA / AT

Request to use results of earlier search; reference to that search (if an earlier search has been carried out by or requested from the International Searching Authority):

Date (day/month/year) Number Country (or regional Office)

## Box No. VIII CHECK LIST; LANGUAGE OF FILING

This international application contains the following number of sheets:

request : 4  
description (excluding sequence listing part) : 14  
claims : 14  
abstract : 1  
drawings : 6  
sequence listing part of description : 0

Total number of sheets : 39

This international application is accompanied by the item(s) marked below:

- fee calculation sheet
- separate signed power of attorney
- copy of general power of attorney; reference number, if any:
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- priority document(s) identified in Box No. VI as item(s):
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Figure of the drawings which should accompany the abstract:

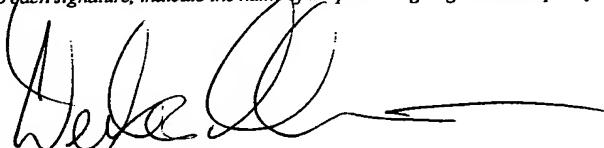
FIGURE 6

Language of filing of the international application:

ENGLISH

## Box No. IX SIGNATURE OF APPLICANT OR AGENT

Next to each signature, indicate the name of the person signing and the capacity in which the person signs (if such capacity is not obvious from reading the request).



DEXTER CHIN

SIEMENS ADVANCED ENGINEERING PTE LTD  
INTELLECTUAL PROPERTY DEPARTMENT

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1. Date of actual receipt of the purported international application: 17 DECEMBER 1999 (17-12-1999)

2. Drawings:

received:

3. Corrected date of actual receipt due to later but timely received papers or drawings completing the purported international application:

not received:

4. Date of timely receipt of the required corrections under PCT Article 11(2):

5. International Searching Authority (if two or more are competent): ISA / AT

6.  Transmittal of search copy delayed until search fee is paid.

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See Notes to the request form

## ENCAPSULATION FOR ORGANIC LED DEVICE

### Field of the Invention

The present invention relates to organic LED (OLED) devices. More particularly, the invention relates to packaging of OLED devices.

### Background of the Invention

Fig. 1 shows an OLED device 100. The OLED device 10 comprises one or more organic functional layers 110 between first and second electrodes 105 and 115. The electrodes can be patterned to form, for example, a plurality of OLED cells to create a pixelated OLED device. Bond pads 150, which are coupled to the first and second electrodes, are provided to enable electrical connections to the OLED cells.

To protect the OLED cells from the environment such as moisture and/or air, a cap 160 encapsulates the device. The active and electrode materials of the OLED cells are sensitive and can be easily damaged due to mechanical contact with, for example, the cap. To prevent damage to the OLED cells, a cavity cap or package is used. The cavity package provides a cavity 145 between the cap and OLED cells. The cavity also

allows for the placement of desiccant materials to cope with finite leakage rate of the device.

Typically, the lateral dimensions of OLED devices are usually in the range of a few centimeters or more, 5 depending on the applications. Typically, the lateral dimensions are larger for displays or lighting devices. To accommodate the large lateral dimensions, thicker caps are used to provide the necessary mechanical stability to maintain the integrity of the cavity.

10 However, the demand for thin and flexible devices requires the use of thinner components, such as the cap and the substrate. Decreasing the thickness of the cap reduces its mechanical stability, making it more prone to bending which can cause the cavity to collapse, 15 thereby damaging the OLED cells.

As evidenced from the above discussion, it is desirable to provide an OLED device having improved packaging, particularly those formed on thin or flexible substrates.

20

#### Summary of the Invention

The invention relates to encapsulation for devices such as OLED devices. One or more OLED cells are provided in the device region of the substrate. A cap

is mounted on the substrate to encapsulate the device.

The cap forms a cavity in the device region, separating it from the OLED cells.

In accordance with the invention, spacer particles  
5 are provided in the device region to prevent the cap from contacting the OLED cells. In one embodiment, the spacer particles are randomly deposited on the substrate by spraying techniques. In one embodiment, the spacer particles are deposited by a dry spray technique.  
10 Alternatively, a wet spray technique is employed to deposit the spacer particles on the substrate. Spacer particles in the non-device region are removed, leaving the spacer particles randomly distributed in the device region. A cap is mounted on the substrate to  
15 encapsulate the device. The spacer particles in the device region prevent the cap from contacting the OLED cells.

Brief Description of the Drawings

20 Fig. 1 shows an OLED device; and

Figs. 2-6 show a process for forming an OLED device in accordance with one embodiment of the invention.

Preferred Embodiments of the Invention

The invention relates generally to OLED devices. In particular, the invention provides a cost-effective package for encapsulating OLED devices, particularly those formed on flexible or thin substrates. In accordance with one embodiment of the invention, spacer particles are provided between the OLED cells and the cap. The spacer particles prevent the cap from contacting the OLED cells.

10 Figs. 2-6 show a process for fabricating an OLED device in accordance with one embodiment of the invention. Referring to Fig. 2, a substrate 201 is provided on which OLED cell or cells are formed. The substrate can comprise various types of materials, such as glass or polymer. Other materials which can adequately support the OLED cells are also useful.

15 In one embodiment, the substrate comprises a flexible material, such as a plastic film for forming a flexible device. Various commercially available plastic films can be used to serve as the substrate. Such films, for example, include transparent poly(ethylene terephthalate) (PET), poly(butylene terephthalate) (PBT), poly(ethylene naphthalate) (PEN), polycarbonate (PC), polyimides (PI), polysulfones (PSO), and poly(p-

phenylene ether sulfone) (PES). Other materials such as polyethylene (PE), polypropylene (PP), poly(vinyl chloride) (PVC), polystyrene (PS) and poly(methyl methacrylate) (PMMA), can also be used to form the 5 substrate. A flexible substrate comprising thin glass or other flexible materials is also useful.

In one embodiment, the substrate is about 20 - 300 um thick. In some cases, the thin substrate maybe mechanically unstable, creating processing problems. A 10 temporary support layer (not shown) can be employed to stabilize the substrate during the fabrication process. The temporary support layer, for example, can be provided on the backside of the substrate. In one embodiment, the temporary support layer comprises a 15 polymer foil coated with an adhesive for attaching to the substrate. After processing, the temporary layer is removed since the device package can be used to mechanically stabilize the device.

A conductive layer 205 is deposited on the 20 substrate. The substrate can be provided with a barrier layer, such as silicon dioxide ( $\text{SiO}_2$ ), beneath the conductive layer on the substrate surface prior to depositing the conductive. Barrier layers are particularly useful for substrates comprising soda lime

glass. The barrier layer, for example, is about 20 nm thick. In one embodiment, the conductive layer comprises a transparent conductive material, such as indium-tin-oxide (ITO). Other types of transparent conductive layers, including zinc-oxide and indium-zinc-oxide, are also useful. Various techniques, such as chemical vapor deposition (CVD) physical vapor deposition (PVD), and plasma enhanced CVD (PECVD), can be employed to form the device layer. The conductive layer should be thin to reduce optical absorption and negative impact on subsequent film formation while satisfying electrical requirements. The conductive layer is typically about 0.02 - 1  $\mu\text{m}$  thick.

Referring to Fig 3, the conductive layer 205 is patterned as desired to selectively remove portions of the layer, exposing portions 356 of the substrate. The patterned conductive layer serves as first electrodes for the OLED cells. In one embodiment, the conductive layer is patterned to form strips that serve as, for example, anodes of a pixelated OLED device. The patterning process can also form connections for bond pads. Conventional techniques, such as photolithography and etching, can be used to pattern the conductive layer. Patterning techniques using a stamp are also

useful. Such techniques are described in co-pending international patent application titled "Mechanical Patterning of a Device Layer" (attorney docket number 99E 8062), which is herein incorporated by reference for 5 all purposes.

One or more organic functional layers 310 are formed on the substrate, covering the exposed substrate portions and conductive layer. The functional organic layers comprise, for example, conjugated polymer or low 10 molecular materials such as Alq<sub>3</sub>. Other types of functional organic layers are also useful. The organic functional layers can be formed by conventional techniques, for example, wet processes such as spin coating or vacuum sublimation (for Alq<sub>3</sub> organic layers). 15 The thickness of the organic layers is typically about 2 - 200 nm.

Referring to Fig. 4, portions of the organic layers can be selectively removed to expose underlying layers in regions 470 for bond pad connections. Selective 20 removal of the organic layers can be achieved using, for example, a polishing process. Other techniques, such as etching, scratching, or laser ablation, are also useful.

In accordance with one embodiment of the invention, spacer particles 480 are deposited on the substrate. In

one embodiment, the spacer particles comprise a spherical shape. Spacer particles having other geometric shapes, such as cubical, prism, pyramidal, or other regular or irregular shapes are also useful. The 5 average mean diameter of the spacer particles is sufficient to maintain the desired height of the cavity, which for example is about 2 - 50  $\mu\text{m}$ . The size and shape distribution of the spacer particles should be sufficiently narrow to ensure proper separation between 10 the cap and OLED cells.

In one embodiment, the spacer particles are randomly distributed on the substrate. Preferably, the spacer particles are randomly distributed in the cell region in which OLED cells are formed. The spacer 15 particles occupy active and non-active parts (e.g., emitting and non-emitting areas) of the device. The distribution or density of the spacer particles should be sufficient to prevent the cap from contacting the OLED cells in the presence of mechanical stress, whether 20 by designed (flexible devices) or accident (handling of the devices). The distribution can be varied to accommodate design requirements, such as the thickness of the 1 cap, thickness of the substrate, and amount of device flexibility needed.

In a preferred embodiment, the spacer distribution is sufficient to maintain the height of the cavity without visibly effecting the emission uniformity of the OLED cells. Typically, a spacer distribution having an 5 average distance between spacer particles of about 10 - 500  $\mu\text{m}$  is adequate in preventing the cap from contacting the OLED cells. In one embodiment, the density of the spacer particle distribution is about 10 - 1000 No/ $\text{mm}^2$ . Such a distribution along with the small size of the 10 spacer particles ensures that their influence on emission uniformity is essentially invisible to the unaided human eye.

To avoid causing shorts between the electrodes, the spacer particles preferably comprise a non-conductive 15 material. In one embodiment, the spacer particles are made of glass. Spacer particles made of other types of non-conductive materials, such as silica, polymers, or ceramic, are also useful.

In embodiment, the spacer particles are deposited 20 by spraying techniques. In a preferred embodiment, a dry spray technique is employed to deposit the spacer particles. Dry spray techniques are described in, for example, Birenda Bahadur (Ed), Liquid Crystals:

Applications and Uses, Vol. 1 (ISBN 9810201109), which is incorporated by reference for all purposes.

Dry spray techniques typically comprise electrostatically charging the spacer particles with a 5 first polarity (positive or negative) and the substrate with a second polarity (negative or positive). The spacer particles are blown against the substrate with dry air supplied by a dry air sprayer. Dry air sprayers, such as a DISPA- $\mu$ R from Nissin Engineering 10 Co., can be used. Electrostatic attraction causes the spacer particles to adhere to the substrate while electrostatic repulsion between the particles prevents particle agglomeration on the substrate. A particle density of 160-180 No/mm<sup>2</sup> can be achieved using a dry air 15 sprayer which generates dry air, for example, having a dew point  $\leq$  -58°C at pressure of 2 kg/cm<sup>2</sup> and a current of 50 l/min for 10 s spray duration. By varying the spraying parameters, other particle densities can be achieved.

20 The use of a wet spray technique to deposit the spacer particles on the substrate is also useful. Wet spray techniques are described in, for example, Birenda Bahadur (Ed), Liquid Crystals: Applications and Uses, Vol. 1 (ISBN 9810201109), which is already incorporated

by reference for all purposes. Typically, the spacer particles are suspended in an alcoholic or aqueous liquids, such as ethanol, isopropanol, or a mixture comprising alcohol and water. The spacer concentration, 5 for example, is about 0.1-0.5% by weight. Ultrasonic waves can be used to disperse the particles to prevent agglomeration. For example, the spacer particles can be irradiated with ultrasonic waves for several minutes prior to particle deposition. The prepared suspension 10 is sprayed with air through a nozzle onto the substrate, depositing the spacer particles thereon.

Referring to Fig. 5, a second conductive layer is deposited on the substrate, covering the spacer particles and other layers formed thereon. The 15 conductive layer comprises, for example, a metallic material such as Ca, Mg, Ba, Ag or a mixture or alloy thereof. Other conductive materials, particularly those which comprises a low work function, can also be used to form the second conductive layer. In one embodiment, 20 the second conductive layer is patterned to form electrode strips that serve as cathode for a pixelated OLED device. Also, connections for bond pads can be formed during the patterning process. Alternatively, the conductive layer can be selectively deposited to

form cathode strips and bond pad connections. Selective deposition of the conductive layer can be achieved with, for example, mask layers. The cathode strips are typically orthogonal to the anode strips. Forming 5 cathode strips that are diagonal to the anode strips is also useful. The intersections of the top and bottom electrode strips form organic LED pixels.

Referring to Fig. 6, a cap 660 is mounted on the substrate to encapsulate the device. The cap layer 10 comprises, for example, metal or glass. Other types of cap which protect the active components from the environment, such as ceramic or metallized foil, are also useful. Various techniques can be used to mount the cap layer. In one embodiment, an adhesive is used 15 to mount the cap layer. Adhesives such as self-hardening adhesives, UV or thermal curable adhesives, or hot melt adhesives are useful. Other techniques which employ low temperature solder materials, ultrasonic bonding, or welding techniques using inductance or laser 20 welding are also useful.

The cap creates a cavity 645, providing separation between it and the OLED cells. During the mounting process, the spacer particles may be pressed into the layers of the OLED cells. The spacer particles provide

support for the cap over the area of the OLED cells, preventing the cap from contacting the active components of the device when pressure is applied to the cap. Bond pads 650 are formed to provide electrical access to the 5 OLED cells.

As described, the process deposits the spacer particles after formation of the organic layers. The spacer particles can alternatively be deposited at other points in the process flow. For example, the spacer 10 particles can be deposited before the formation of the first conductive layer, before the formation of the organic layers, or after the formation of the second conductive layer. In effect, the spacer particles can be deposited at any point of the process prior to 15 mounting of the cap.

Spacer particles can also be useful in providing support in other types of devices that employ cavity packages. Such devices include, for example, electrical devices, mechanical devices, electromechanical devices, 20 or microelectromechanical systems (MEMS).

While the invention has been particularly shown and described with reference to various embodiments, it will be recognized by those skilled in the art that modifications and changes may be made to the present

invention without departing from the spirit and scope thereof. The scope of the invention should therefore be determined not with reference to the above description but with reference to the appended claims along with  
5 their full scope of equivalents.

What is claimed is:

1. A device comprising :

a substrate with a device region;

5 a cap for encapsulating the device, the cap creates a cavity over the device region; and

spacer particles in the device region to support the cap.

10 2. The device of claim 1 wherein the device region comprises one or more cells.

3. The device of claim 2 wherein the spacer particles comprise a non-conductive material.

15

4. The device of claim 1 wherein the spacer particles comprise a non-conductive material.

5. The device of claim 1, 2, 3, or 4 wherein 2 the  
20 spacer particles are randomly distributed in the device region, occupying active and non-active regions.

6. The device of claim 5 wherein the spacer particles comprise a spherical shape.

7. The device of claim 6 wherein the spacer particles comprises a mean diameter to maintain a height of the cavity between the cap and substrate.

5

8. The device of claim 7 wherein the spacer particles comprise a density to maintain the cavity.

9. The device of claim wherein the density of the  
10 spacer particles is about 10 - 1000 No/mm<sup>2</sup>.

10. The device of claim 5 wherein the spacer particles comprise a non-spherical shape.

15 11. The device of claim 10 wherein the spacer particles comprise different shapes.

12. The device of claim 11 wherein the spacer particles comprises a mean diameter to maintain a height of the  
20 cavity between the cap and substrate.

13. The device of claim 12 wherein the spacer particles comprise a density to maintain the cavity.

14. The device of claim 13 wherein the density of the spacer particles is about 10 - 1000 No/mm<sup>2</sup>.

15. The device of claim 10 wherein the spacer particles  
5 comprises a mean diameter to maintain a height of the cavity between the cap and substrate.

16. The device of claim 15 wherein the spacer particles comprise a density to maintain the cavity.

10

17. The device of claim 16 wherein the density of the spacer particles is about 10 - 1000 No/mm<sup>2</sup>.

18. The device of claim 5 wherein the spacer particles  
15 comprises a mean diameter to maintain a height of the cavity between the cap and substrate.

19. The device of claim 18 wherein the spacer particles comprise a density to maintain the cavity.

20

20. The device of claim 19 wherein the density of the spacer particles is about 10 - 1000 No/mm<sup>2</sup>.

21. The device of claim 5 wherein the spacer particles comprise a density to maintain the cavity.

22. The device of claim 21 wherein the density of the  
5 spacer particles is about 10 - 1000 No/mm<sup>2</sup>.

23. A method for forming a device comprises:  
providing a substrate with a device region;  
depositing spacer particles on the substrate and  
10 mounting a cap on the substrate to encapsulate the  
device, the cap forms a cavity in the device region  
supported by spacer particles.

24. The method of claim 23 wherein the device comprises  
15 an OLED device.

25. The method of claim 24 wherein the substrate is  
prepared with a conductive layer patterned to form first  
electrodes and at least one organic functional layer  
20 over the conductive layer.

26. The method of claim 25 wherein the conductive layer  
comprises a transparent conductive material.

27. The method of claim 26 wherein the spacer particles comprise a non-conductive material.

28. The method of claim 25 wherein the spacer particles  
5 comprise a non-conductive material.

29. The method of claim 24 wherein the substrate is prepared with at least one OLED cell in the device region.

10

30. The method of claim 29 wherein the spacer particles comprise a non-conductive material.

31. The method of claim 23 wherein the spacer particles  
15 comprise a non-conductive material.

32. The method of claim 24 wherein the spacer particles comprise a non-conductive material.

20 33. The method of claim 27 wherein depositing the spacer layers depositing the spacer layers by dry spraying

34. The method of claim 33 wherein the dry spraying comprises:

electrostatically charging the substrate with a first polarity and the spacer particles with a second  
5 polarity; and

blowing the spacer particles against the substrate with dry air.

35. The method of claim wherein 34 the dry air  
10 comprises a dew point of  $\leq 58^{\circ}\text{C}$ .

36. The method of claim wherein 28 depositing the spacer particles comprises dry spraying

15 37. The method of claim 36 wherein the dry spraying comprises:

electrostatically charging the substrate with a first polarity and the spacer particles with a second  
polarity; and

20 blowing the spacer particles against the substrate with dry air.

38. The method of claim wherein 37 the dry air comprises a dew point of  $\leq 58^{\circ}\text{C}$ .

39. The method of claim wherein 30 depositing the spacer particles comprises dry spraying.

5 40. The method of claim 39 wherein the dry spraying comprises:

electrostatically charging the substrate with a first polarity and the spacer particles with a second polarity; and

10 blowing the spacer particles against the substrate with dry air.

41. The method of claim wherein 40 the dry air comprises a dew point of  $\leq 58^{\circ}\text{C}$ .

15

42. The method of claim wherein 23 depositing the spacer particles comprises dry sprayings

43. The method of claim 42 wherein the dry spraying  
20 comprises:

electrostatically charging the substrate with a first polarity and the spacer particles with a second polarity; and

blowing the spacer particles against the substrate with dry air.

44. The method of claim wherein 43 the dry air  
5 comprises a dew point of  $\leq 58^{\circ}\text{C}$ .

45. The method of claim wherein 23 depositing the spacer particles comprises dry spraying.

10 46. The method of claim 45 wherein the dry spraying comprises:

electrostatically charging the substrate with a first polarity and the spacer particles with a second polarity; and

15 blowing the spacer particles against the substrate with dry air.

47. The method of claim wherein 46 the dry air comprises a dew point of  $\leq 58^{\circ}\text{C}$ .

48. The method of claim wherein 32 depositing the spacer particles comprises dry spraying.

49. The method of claim 48 wherein the dry spraying comprises:

electrostatically charging the substrate with a first polarity and the spacer particles with a second 5 polarity; and

blowing the spacer particles against the substrate with dry air.

50. The method of claim wherein 49 the dry air 10 comprises a dew point of  $\leq 58^{\circ}\text{C}$ .

51. The method of claim 23 wherein depositing the spacer particles comprises wet spraying.

15 52. The method of claim 51 wherein the wet spraying comprises:

Suspending spacer particles in a solution; and  
Spraying the solution with spacer particles on the substrate.

20

53. The method of claim 52 wherein the solution comprises a concentration of spacer particles of about 0.1 - 0.5 weight percent.

54. The method of claim 27 wherein depositing the spacer particles comprises wet spraying.

55. The method of claim 54 wherein the wet spraying  
5 comprises:

Suspending spacer particles in a solution; and  
Spraying the solution with spacer particles on the substrate.

10 56. The method of claim 55 wherein the solution comprises a concentration of spacer particles of about 0.1 - 0.5 weight percent.

15 57. The method of claim 28 wherein depositing the spacer particles comprises wet spraying.

58. The method of claim 57 wherein the wet spraying comprises:

Suspending spacer particles in a solution; and  
20 Spraying the solution with spacer particles on the substrate.

59. The method of claim 58 wherein the solution comprises a concentration of spacer particles of about 0.1 - 0.5 weight percent.

5 60. The method of claim 30 wherein depositing the spacer particles comprises wet spraying.

61. The method of claim 60 wherein the wet spraying comprises:

10 Suspending spacer particles in a solution; and  
Spraying the solution with spacer particles on the substrate.

62. The method of claim 61 wherein the solution comprises a concentration of spacer particles of about 0.1 - 0.5 weight percent.

63. The method of claim 32 wherein depositing the spacer particles comprises wet spraying.

20 64. The method of claim 63 wherein the wet spraying comprises:  
Suspending spacer particles in a solution; and

Spraying the solution with spacer particles on the substrate.

65. The method of claim 64 wherein the solution  
5 comprises a concentration of spacer particles of about  
0.1 - 0.5 weight percent.

66. The method of claim 23, 24, 25, 26, 27, 28, 29, 30,  
31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 42, 43, 44,  
10 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58,  
59, 60, 61, 62, 63, 64 or 65 wherein spacer particles  
are randomly deposited on the substrate.

67. The method of claim 66 further comprises removing  
15 spacer particles from non-device region of the substrate  
for mounting of the cap.

68. The method of claim 67 wherein the spacer particles  
comprise a spherical shape.

20

69. The method of claim 68 wherein the spacer particles  
comprise a mean diameter maintain a height of the cavity  
between the cap and substrate.

70. The method of claim 69 wherein the spacer particles are deposited on the substrate with a density to maintain the cavity.

5 71. The method of claim 70 wherein the spacer particles comprise a non-spherical shape.

72. The method of claim 71 the spacer particles comprises different shapes.

10

73. The method of claim 72 wherein the spacer particles comprise a mean diameter maintain a height of the cavity between the cap and substrate.

15 74. The method of claim 73 wherein the spacer particles are deposited on the substrate with a density to maintain the cavity.

75. The method of claim 71 wherein the spacer particles  
20 comprise a mean diameter maintain a height of the cavity between the cap and substrate.

76. The method of claim 75 wherein the spacer particles are deposited on the substrate with a density to maintain the cavity.

5 77. The method of claim 67 wherein the spacer particles comprise a mean diameter maintain a height of the cavity between the cap and substrate.

78. The method of claim 77 wherein the spacer particles  
10 are deposited on the substrate with a density to maintain the cavity.

79. The method of claim 67 wherein the spacer particles are deposited on the substrate with a density to  
15 maintain the cavity.

**ABSTRACT**

An encapsulation for a device is disclosed. Spacer particles are randomly located in the device region to prevent a cap mounted on the substrate from contacting the active components, thereby protecting them from damage.

1 of 6

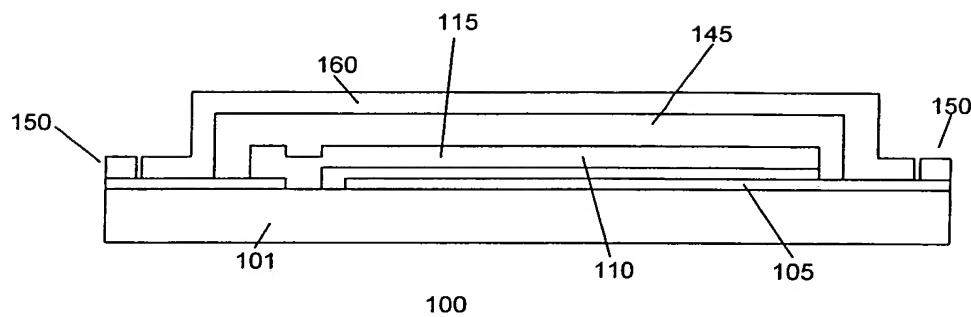


Fig. 1

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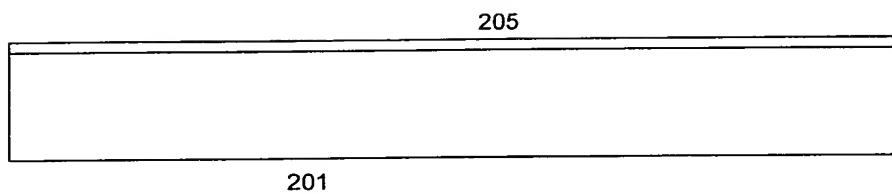


Fig. 2

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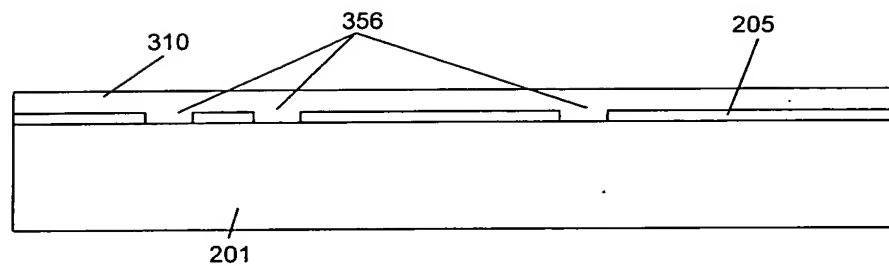


Fig. 3

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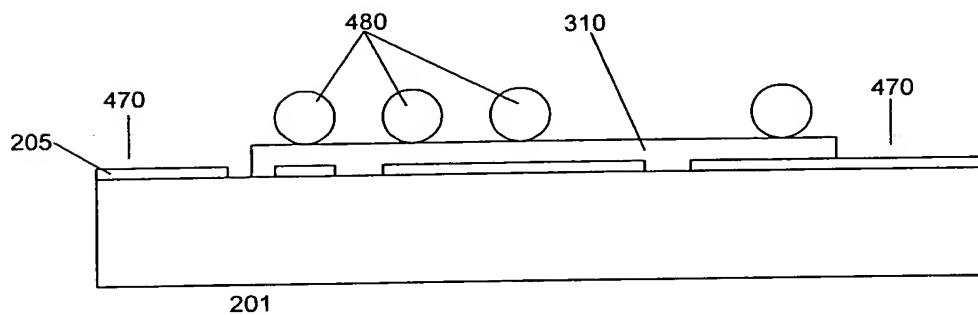


Fig. 4

5 of 6

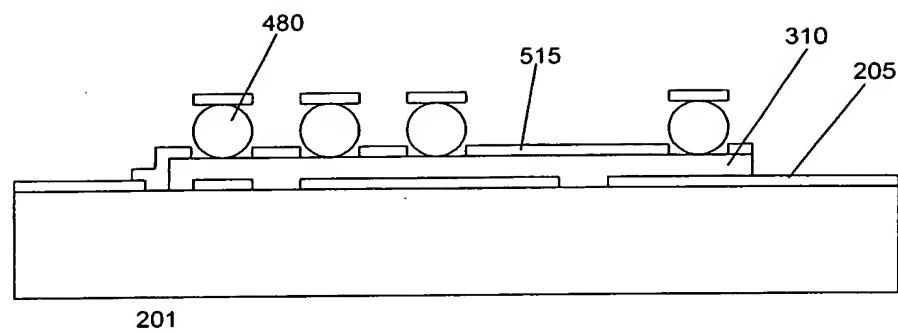


Fig. 5

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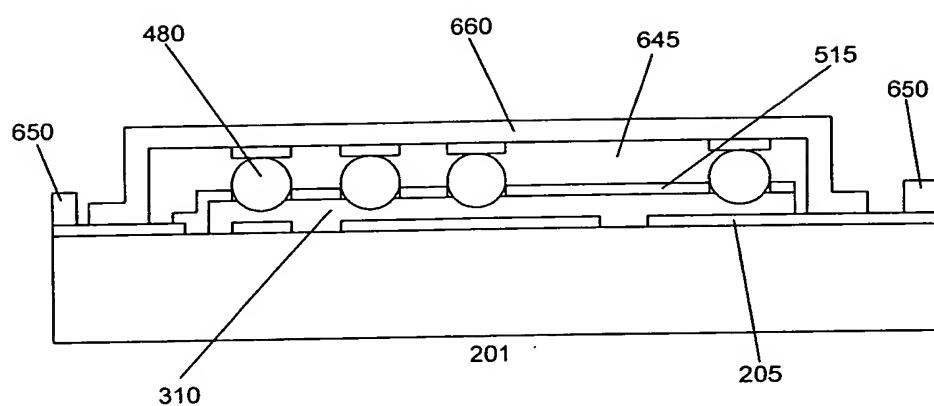


Fig. 6